

Title (en)

CLEANING LEAD-FRAMES TO IMPROVE WIREBONDING PROCESS

Title (de)

REINIGUNG VON FÜHRUNGSRahmen ZUR VERBESSERUNG EINES DRAHTBINDUNGSVERFAHRENS

Title (fr)

NETTOYAGE DE GRILLES DE CONNEXION POUR AMÉLIORER LE PROCESSUS DE SOUDAGE FILAIRE

Publication

EP 2702607 A4 20150624 (EN)

Application

EP 12776905 A 20120425

Priority

- US 201161478582 P 20110425
- US 2012034912 W 20120425

Abstract (en)

[origin: WO2012148967A2] A method of processing a semiconductor substrate to remove undesired material therefrom or to prepare a surface of the semiconductor substrate for subsequent bonding wherein the substrate comprises a leadframe comprising dies, bond pads, contacts, and wires, the method comprises the step of contacting the substrate with a liquid cleaning composition and compositions useful in the method.

IPC 8 full level

H01L 21/48 (2006.01); **B08B 3/08** (2006.01); **C11D 3/20** (2006.01); **C11D 7/26** (2006.01); **C11D 11/00** (2006.01); **H01L 21/60** (2006.01)

CPC (source: CN EP)

C11D 7/265 (2013.01 - EP); **H01L 21/4835** (2013.01 - CN EP); **H01L 24/05** (2013.01 - EP); **H01L 24/85** (2013.01 - CN EP); **H01L 24/97** (2013.01 - EP); **C11D 2111/22** (2024.01 - EP); **H01L 23/3107** (2013.01 - EP); **H01L 24/29** (2013.01 - EP); **H01L 24/32** (2013.01 - EP); **H01L 24/45** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/73** (2013.01 - EP); **H01L 24/92** (2013.01 - EP); **H01L 24/94** (2013.01 - EP); **H01L 2224/0381** (2013.01 - EP); **H01L 2224/04042** (2013.01 - EP); **H01L 2224/05624** (2013.01 - EP); **H01L 2224/05647** (2013.01 - EP); **H01L 2224/291** (2013.01 - EP); **H01L 2224/2919** (2013.01 - EP); **H01L 2224/32225** (2013.01 - EP); **H01L 2224/32245** (2013.01 - EP); **H01L 2224/45124** (2013.01 - EP); **H01L 2224/45139** (2013.01 - EP); **H01L 2224/45144** (2013.01 - EP); **H01L 2224/45147** (2013.01 - CN EP); **H01L 2224/48227** (2013.01 - EP); **H01L 2224/48247** (2013.01 - CN EP); **H01L 2224/48463** (2013.01 - EP); **H01L 2224/4847** (2013.01 - EP); **H01L 2224/48624** (2013.01 - EP); **H01L 2224/48647** (2013.01 - EP); **H01L 2224/48724** (2013.01 - EP); **H01L 2224/48747** (2013.01 - EP); **H01L 2224/48824** (2013.01 - EP); **H01L 2224/48847** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/83011** (2013.01 - EP); **H01L 2224/83022** (2013.01 - EP); **H01L 2224/83191** (2013.01 - EP); **H01L 2224/83192** (2013.01 - EP); **H01L 2224/83193** (2013.01 - EP); **H01L 2224/83855** (2013.01 - EP); **H01L 2224/8501** (2013.01 - CN EP); **H01L 2224/85011** (2013.01 - EP); **H01L 2224/92247** (2013.01 - EP); **H01L 2224/94** (2013.01 - EP); **H01L 2224/97** (2013.01 - EP); **H01L 2924/01005** (2013.01 - CN EP); **H01L 2924/01006** (2013.01 - CN EP); **H01L 2924/01012** (2013.01 - CN EP); **H01L 2924/01013** (2013.01 - CN); **H01L 2924/01019** (2013.01 - CN EP); **H01L 2924/0102** (2013.01 - CN EP); **H01L 2924/01023** (2013.01 - CN EP); **H01L 2924/01024** (2013.01 - CN); **H01L 2924/01025** (2013.01 - CN); **H01L 2924/01029** (2013.01 - CN EP); **H01L 2924/0103** (2013.01 - CN EP); **H01L 2924/01033** (2013.01 - CN EP); **H01L 2924/01047** (2013.01 - CN EP); **H01L 2924/0105** (2013.01 - CN EP); **H01L 2924/01075** (2013.01 - CN EP); **H01L 2924/01079** (2013.01 - CN EP); **H01L 2924/01082** (2013.01 - CN EP); **H01L 2924/01327** (2013.01 - CN EP); **H01L 2924/014** (2013.01 - CN EP); **H01L 2924/10253** (2013.01 - CN EP); **H01L 2924/14** (2013.01 - EP); **H01L 2924/1461** (2013.01 - EP); **H01L 2924/15311** (2013.01 - EP); **H01L 2924/15747** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP)

C-Set (source: CN EP)

CN

1. **H01L 2224/45147** + **H01L 2924/00**
2. **H01L 2924/10253** + **H01L 2924/00**

EP

1. **H01L 2924/10253** + **H01L 2924/00**
2. **H01L 2224/45144** + **H01L 2924/00014**
3. **H01L 2224/45147** + **H01L 2924/00014**
4. **H01L 2224/45139** + **H01L 2924/00014**
5. **H01L 2224/45124** + **H01L 2924/00014**
6. **H01L 2924/1461** + **H01L 2924/00**
7. **H01L 2224/73265** + **H01L 2224/32225** + **H01L 2224/48227** + **H01L 2924/00012**
8. **H01L 2224/73265** + **H01L 2224/32245** + **H01L 2224/48247** + **H01L 2924/00012**
9. **H01L 2224/291** + **H01L 2924/014**
10. **H01L 2224/94** + **H01L 2224/03**
11. **H01L 2224/97** + **H01L 2224/83**
12. **H01L 2224/97** + **H01L 2224/85**
13. **H01L 2224/48624** + **H01L 2924/00**
14. **H01L 2924/15311** + **H01L 2224/73265** + **H01L 2224/32225** + **H01L 2224/48227** + **H01L 2924/00**
15. **H01L 2224/92247** + **H01L 2224/73265** + **H01L 2224/32225** + **H01L 2224/48227** + **H01L 2924/00**
16. **H01L 2224/92247** + **H01L 2224/73265** + **H01L 2224/32245** + **H01L 2224/48247** + **H01L 2924/00**
17. **H01L 2924/15747** + **H01L 2924/00**
18. **H01L 2924/181** + **H01L 2924/00**
19. **H01L 2224/48824** + **H01L 2924/00**
20. **H01L 2224/48847** + **H01L 2924/00**
21. **H01L 2224/97** + **H01L 2224/73265** + **H01L 2224/32225** + **H01L 2224/48227** + **H01L 2924/00**
22. **H01L 2224/48647** + **H01L 2924/00**
23. **H01L 2224/48724** + **H01L 2924/00**
24. **H01L 2224/48747** + **H01L 2924/00**
25. **H01L 2224/97** + **H01L 2224/73265** + **H01L 2224/32245** + **H01L 2224/48247** + **H01L 2924/00**

Citation (search report)

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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KR 20130142197 A 20131227; MY 175223 A 20200616; SG 194523 A1 20131230; TW 201308455 A 20130216; TW I467675 B 20150101

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